



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PDN# 20201012000.3
Discontinuance of the SN74AVC4T234ZSUR MicroStar BGA and Replacement with nFBGA package device
Product Discontinuance Notification

Date: October 14, 2020
To: MOUSER PCN

Dear Customer:

The recipient has been identified for notification of changes for one or more of the products affected by the change detailed in the notice. Customers are notified based on the past twenty-four (24) months of the customer's purchase history or the recipient is listed as being part of GIDEP (Government-Industry Data Exchange Program).

TI would appreciate it if you would notify us of any future demand and estimated quantities needed for the affected products as soon as possible.

In an attempt to satisfy continuing requirements, TI is offering a non-cancelable, non-refundable last time buy for the product. Related dates are included in the notification. We will contact you as soon as we have completed a review of all customer responses and determined the appropriate course of action required to satisfy the need for this/these products.

Any inquiries should be directed to your local Field Sales Representative.

If additional supply is required beyond the dates defined in this letter, please contact your local Field Sales Representative to determine if the parts may be available from a TI-authorized distributor for discontinued products. There is no guarantee of continued supply for these products.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**20201012000.3
Attachments1**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have purchased this device within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74AVC4T234ZSUR	null

Details of this Product Discontinuance follow on the next page(s).

PDN Number:	20201012000.3	PDN Date:	Oct 14, 2020
Title:	Discontinuance of the SN74AVC4T234ZSUR MicroStar BGA and Replacement with nFBGA package device		
Customer Contact:	PCN Manager	Dept:	Quality Services
Last date to order:	April 14, 2021	Last date to ship:	April 14, 2022
Change Type:	Product Discontinuance - End Of Life		
Product Discontinuance Notification Details			
Description of Discontinuance:			
<p>Texas Instruments, Incorporated (TI) is announcing the discontinuance of the SN74AVC4T234ZSUR MicroStar BGA and the replacement with an nFBGA package device. A non-cancelable, non-refundable last time buy is being offered per the date shown above. Part numbers are shown in the Product Affected section below.</p> <p>The devices in the MicroStar BGA package were redesigned using a laminate BGA package (nFBGA). nFBGA provides the same X and Y dimensions as MicroStar BGA, and provides pin-to-pin and footprint compatibility. However the nFBGA PCB land pattern and stencil recommendations have been updated to achieve better soldering results after extensive testing and evaluation. For more details, please refer to this nFBGA application note.</p>			
BOM for new nFBGA Package:			
	Assembly Site nFBGA		
Assembly Site	TI Philippines		
Mount Compound	film		
Mold compound	4205283		
Wire Type	Cu		
Substrate	Laminate		
<p>NOTE: There are no samples offered for withdrawn/obsolete products. For samples of any replacement products, please contact your local sales representative or visit the TI store at https://www.ti.com/store.</p>			
Reason for Withdrawal/Discontinuance:			
Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA package devices and offering a last time buy.			
Product Affected:			
	RECOMMENDED REPLACEMENT PRODUCTS (nFBGA Package)	REPLACEMENT CODES	
Devices Being Discontinued			
SN74AVC4T234ZSUR	SN74AVC4T234ZWAR	Q	
Replacement Notes:			
F = Similar functionality but not equivalent.			
P = Same functionality but not pin-for-pin equivalent and may not be parametrically equivalent.			
Q = Same functionality and PIN-OUT as the compared device but is NOT an exact equivalent.			
S = EXACT equivalent in functionality and parametrically to the compared device.			

Qualification Report (nFBGA)

Approve Date 8-Jan-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>SN74AVC4T234ZWAR</u>	QBS Process Reference: <u>SN74AVCT234ZSU</u>
PC	Preconditioning	(Level 2-260C)	3/1230/0	-
HTOL	Life Test, 150C	300 hrs	-	3/231/0
HAST	Biased HAST, 110C/85%RH	264 Hours	3/231/0	-
HTSL	High Temp Storage Bake 150C	1000 Hours	3/231/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	-
UHAST	Unbiased HAST 110C/85%RH	264 Hours	3/231/0	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-
CDM	ESD - CDM	750V	2/6/0	-
HBM	ESD - HBM	3000V	2/6/0	-
LU	Latch-up	(per JESD78)	3/18/0	-

- QBS: Qual By Similarity

- Qual Device SN74AVC4T234ZWAR is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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